Amendments to the Specification

Please replace paragraph [0004] with the following amended paragraph.

[0004] Pixilated multi-contact detectors employing semiconductors, such as Si, Ge, HgI, CdTe, and CdZnTe, with readout chips are currently under development in many research laboratories. These detectors are key components in imaging systems with medical, industrial, and scientific applications. For example, the CdZnTe (CZT) semiconductor detector is a device for the imaging and spectroscopy of hard X-rays and low-energy gamma-rays. The CZT detector demonstrates improved room temperature spatial and energy resolution of X-rays. CZT multi-contact detectors are being developed, in one instance, for use in medical scanners and homographs. Typically, each ~~imagining~~ imaging system will require many thousands of individual CZT detectors.

Please replace paragraph [0027] with the following amended paragraph.

[0027] ~~In the bottom diagram of Fig. 3, the base~~ Base 16 contains a thumb wheel 22 which is used for z-axis alignment. The thumb wheel 22 allows the detector or chip 14 to be moved toward the shadow mask 12. A top plate 24 connects the disc 10

to the commercial mask aligner 26 via four screws 24. The shadow mask 12 is held above the detector or chip 14 so that the shadow mask 12 and the detector or chip 14 are not in contact.